

# SOT2088-1(SC)

HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

4 September 2025

Package information



## 1 Package summary

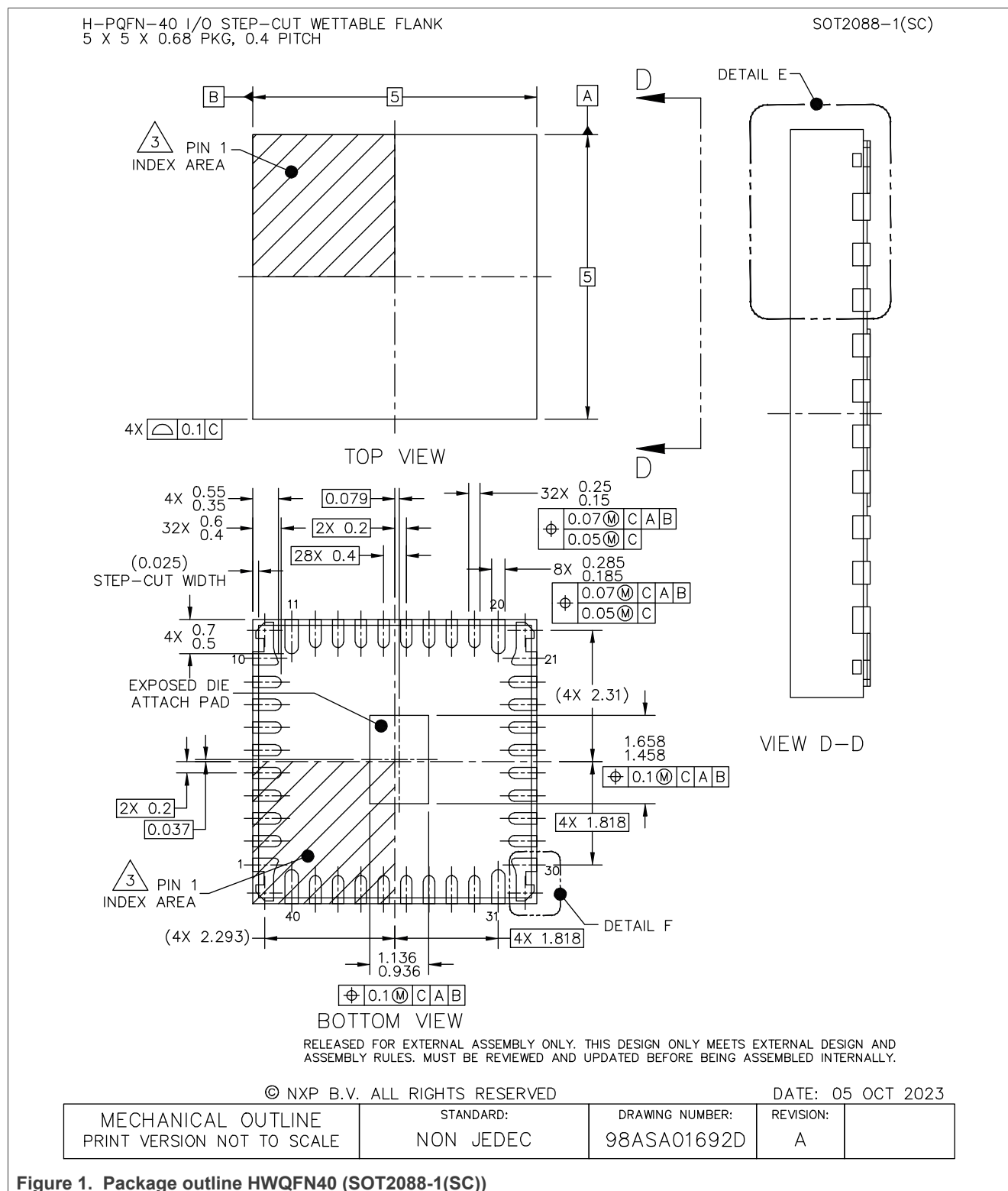
Terminal position code	Q (quad)
Package type descriptive code	HWQFN40
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-10-2023
Manufacturer package code	98ASA01692D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.65	0.68	0.75	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	40	-	

**HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body**

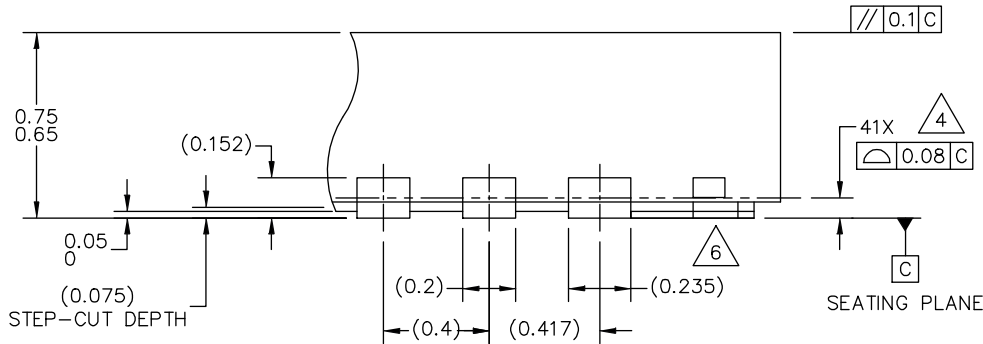
## 2 Package outline



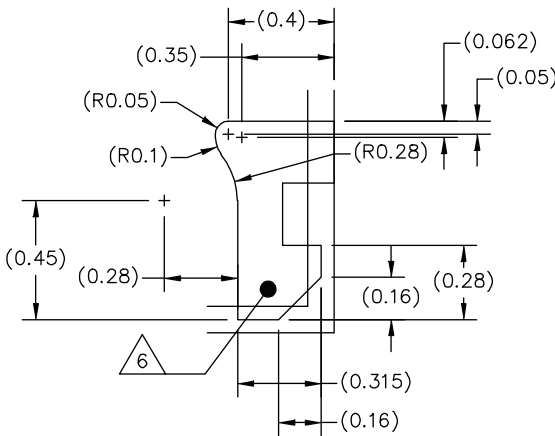
HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-PQFN-40 I/O STEP-CUT WETTABLE FLANK  
5 X 5 X 0.68 PKG, 0.4 PITCH

SOT2088-1(SC)



DETAIL E  
VIEW ROTATED 90° CW



DETAIL F  
4X PLACES

RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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DATE: 05 OCT 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01692D	REVISION: A	
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Figure 2. Package outline detail F of HWQFN40 (SOT2088-1(SC))

HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

3 Soldering

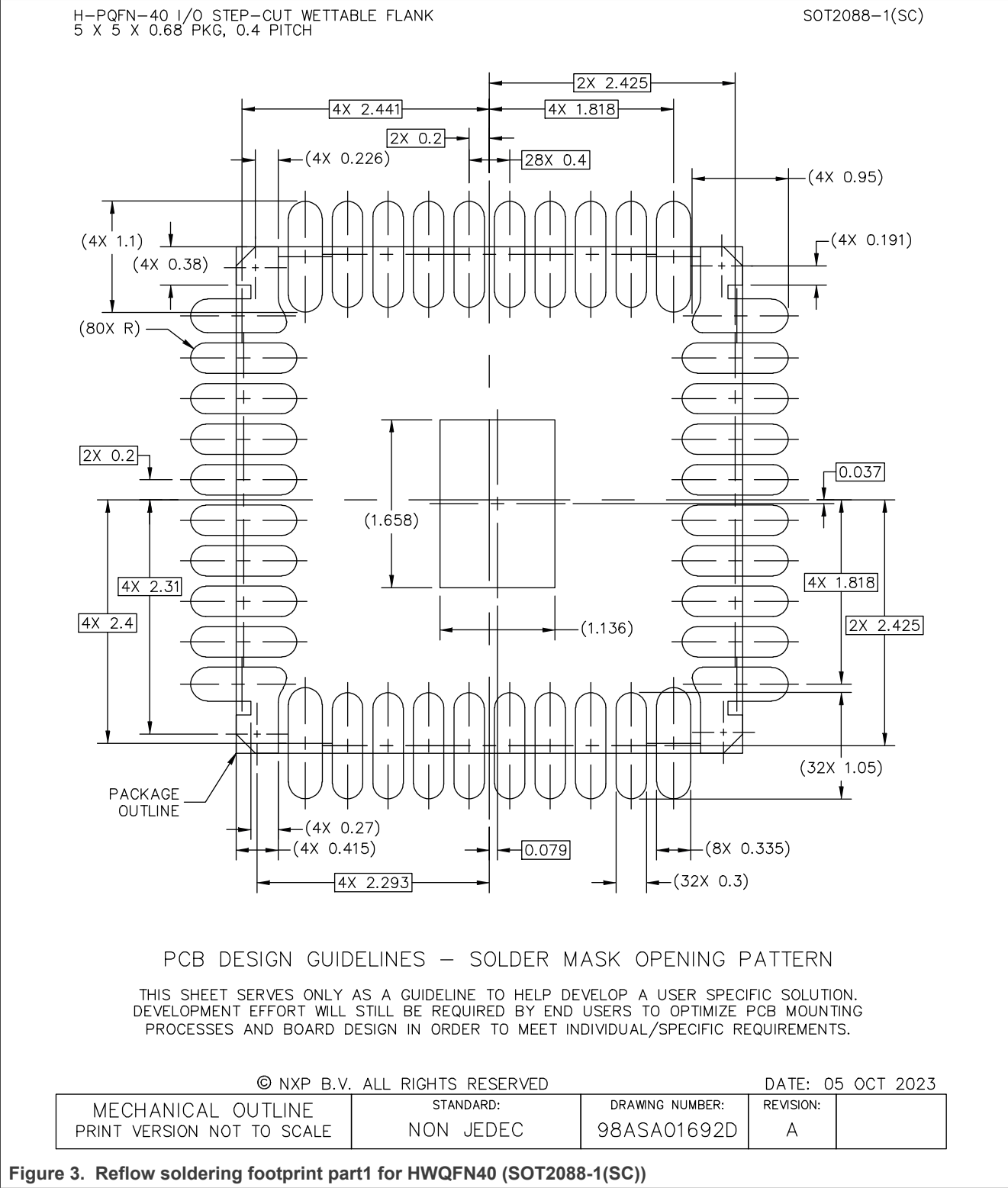
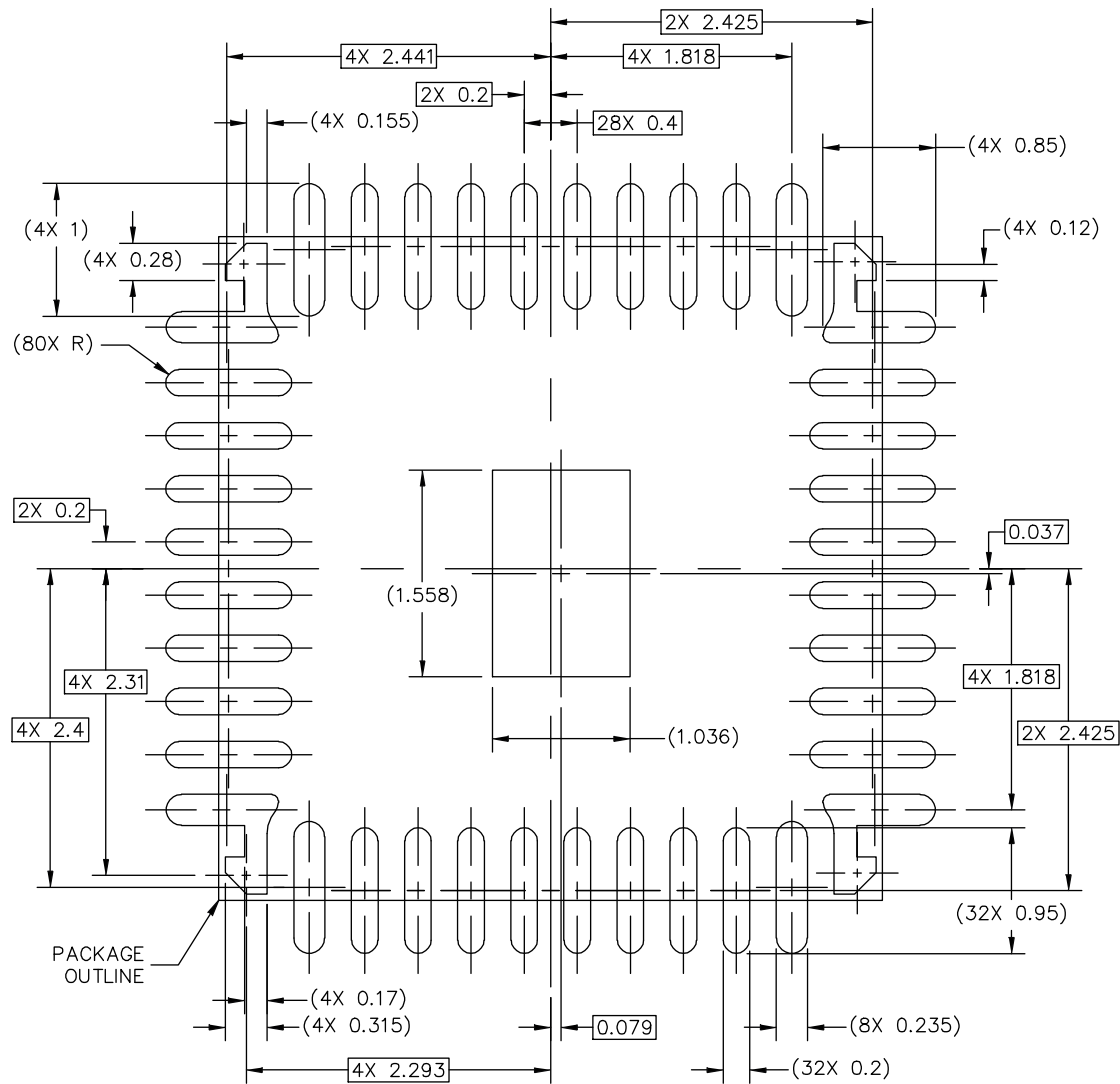


Figure 3. Reflow soldering footprint part1 for HWQFN40 (SOT2088-1(SC))

HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-PQFN-40 I/O STEP-CUT WETTABLE FLANK  
5 X 5 X 0.68 PKG, 0.4 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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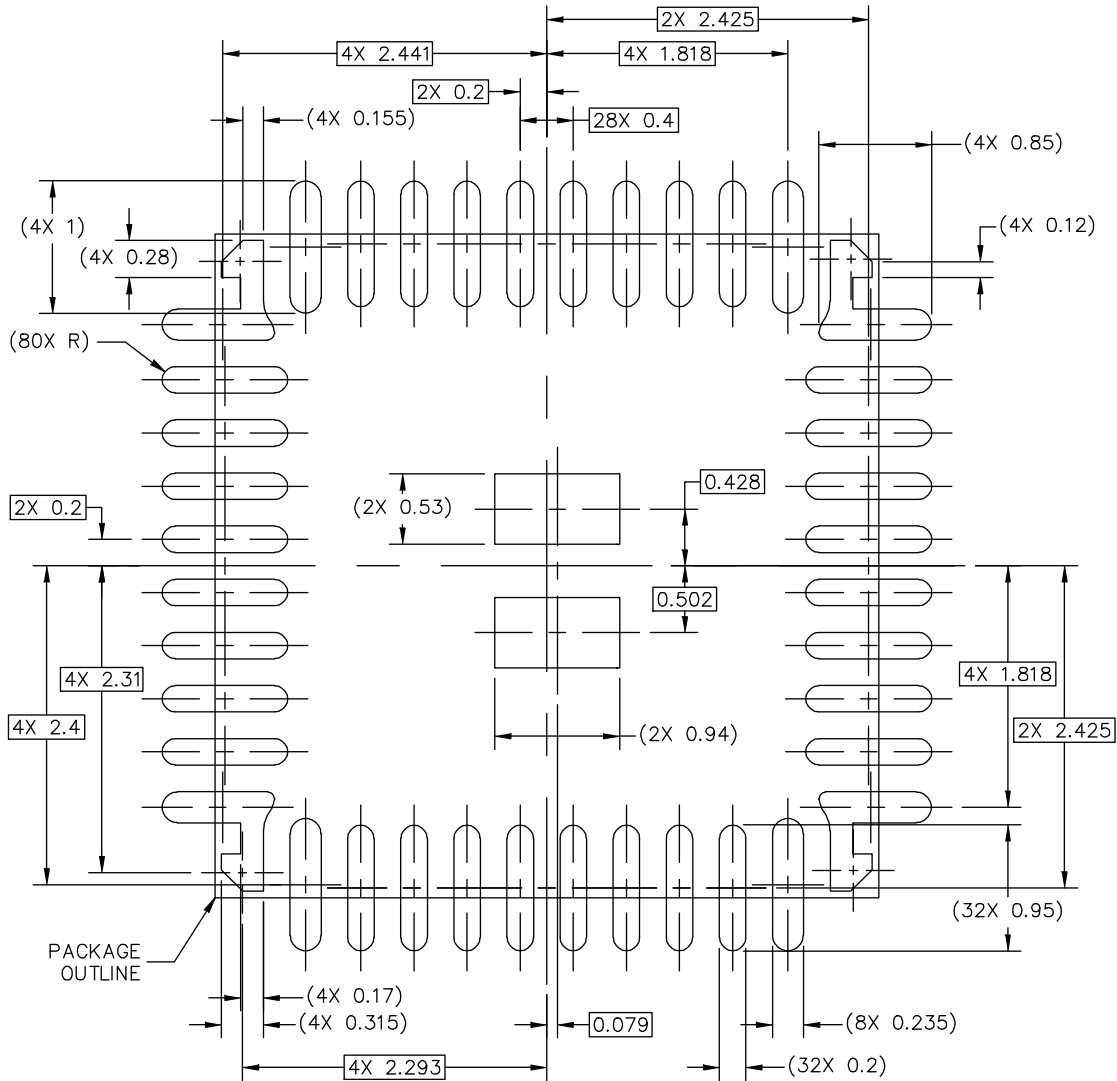
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01692D	REVISION: A
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Figure 4. Reflow soldering footprint part2 for HWQFN40 (SOT2088-1(SC))

HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-PQFN-40 I/O STEP-CUT WETTABLE FLANK  
5 X 5 X 0.68 PKG, 0.4 PITCH

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HWQFN40 (SOT2088-1(SC))

HWQFN40, thermal enhanced very very thin quad flatpack; no leads, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-PQFN-40 I/O STEP-CUT WETTABLE FLANK  
5 X 5 X 0.68 PKG, 0.4 PITCH

SOT2088-1(SC)

- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
  - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
  - 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
  - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
  - 6. ANCHORING PADS.

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Figure 6. Package outline note HWQFN40 (SOT2088-1(SC))

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## 4 Legal information

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